



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  *: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2022-02-10
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	giovanni giacopello	<b>Representative Title</b>	ADG Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b> Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPST15H100SBYTR	ASDP*07VEB50	A	3068	2022-02-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	320	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00737949	

Package Designator	Package Size	Nbr of instances	Shape	
SIP	6.50,6.10,2.30	3	gull wing	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1- Product(s) meets EU RoHS requirement without any exemptions	false
2- Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3- Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4- Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1- Product(s) meets EU ELV requirements without any exemptions	true
2- Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description
8(e)	8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 17th Dec 2021			
Query			Response
1- The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2- The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	2.668	die - leadframe	8338
Lead	2.447	soft solder	7647

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				
Query				Response
1- Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				true
2- Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hasardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
X	O	O	O	O
Soft solder				
Homogeneous Material(s) containing Lead				

QueryList : REACH-17 Jan 2022				
Query				Response
1- Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.45	Soft solder	7647
2- Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.45	Soft solder	955113

QueryList : Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present in the component :	Gold, Tin, Tungsten,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	
Query	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	
Query	Response
The product contains adhesives identified under GB 33372	false

Stockholm Convention Persistent Organic Pollutants	
Query	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	true

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	ASDP*07VE80					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	10.485	mg	supplier	die	Silicon(Si)	7440-21-3		3.215	mg	306629	10045
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.112	mg	10682	350
				supplier	metallisation	Gold(Au)	7440-57-5		6.997	mg	867334	21866
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.064	mg	6104	200
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.011	mg	1049	34
				supplier	metallisation	Tungsten(W)	7440-33-7		0.001	mg	95	3
Leadframe	M-004 Copper and its alloys	235.016	mg	supplier	polymer coating	Durimide	proprietary		0.085	mg	8107	266
				supplier	alloy	Copper(Cu)	7440-50-8		232.036	mg	987320	725113
				supplier	alloy	Iron(Fe)	7439-89-6		0.232	mg	987	725
				supplier	alloy	Iron phosphide	26508-33-8		0.070	mg	298	219
				supplier	metallization	Nickel (Ni)	7440-02-0		2.604	mg	11080	8138
Soft solder	Solder	2.562	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	2.447	mg	955114	7647
				supplier	solder	Silver(Ag)	7440-22-4		0.064	mg	24980	200
				supplier	solder	Tin(Sn)	7440-31-5		0.051	mg	19906	159
				supplier	wire	Aluminium (Al)	7429-90-5		1.662	mg	100000	5194
Bonding wires	M-003 Aluminum and its alloys	1.662	mg	supplier	mold compound	Silica vitreous	60676-86-0		60.576	mg	874997	189300
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		2.769	mg	39977	8653
				supplier	mold compound	Epoxy type resin	proprietary		2.077	mg	30001	6491
				supplier	mold compound	Phenol type resin	proprietary		3.462	mg	50007	10819
Encapsulation	M-011 Other inorganic materials	69.230	mg	supplier	mold compound	Carbon black	1333-86-4		0.346	mg	4998	1081
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266